PRINTED CIRCUIT BOARDS

INTERCONNECTION CARRIERS

State of the Art: PCB's	Revisio	Datum:	Seite:
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Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h+ i
08	199	FR4	60	L12.70	P12_06	

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

08_199_FR4_60_L12.70_p12_06

Layers	in µ	Material	Build-Up	Assembly
Layer-1	35µ	Copper		B
	60µ	Prepreg	(60µ PrePreg-Type: 1080)	
	60µ	Prepreg		
	60µ	Prepreg		
Layer-2	70µ	Copper		A1
	125µ	L-FR4		
Layer-3	70µ	Copper		
	120µ	Prepreg	(120 µ PrePreg-Type: 2116)	
	120µ	Prepreg		
	120µ	Prepreg		
Layer-4	70µ	Copper		A2
	125µ	L-FR4		
Layer-5	70µ	Copper		
	120µ	Prepreg		
	120µ	Prepreg		
	120µ	Prepreg		
Layer-6	70µ	Copper		A3
	125µ	L-FR4		
Layer-7	70µ	Copper		
	60µ	Prepreg		
	60µ	Prepreg		
	60µ	Prepreg		
Layer-99	35µ	Copper		

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